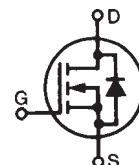


HiperFET™
Power MOSFET
Q3-Class

IXFB44N100Q3

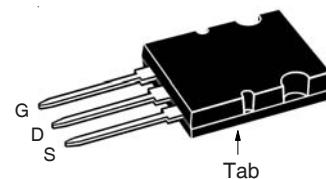
V_{DSS} = 1000V
I_{D25} = 44A
R_{DS(on)} ≤ 220mΩ
t_{rr} ≤ 300ns



N-Channel Enhancement Mode
Fast Intrinsic Rectifier

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	1000	V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ	1000	V
V _{GSS}	Continuous	±30	V
V _{GSM}	Transient	±40	V
I _{D25}	T _C = 25°C	44	A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	110	A
I _A	T _C = 25°C	44	A
E _{AS}	T _C = 25°C	4	J
dv/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 150°C	50	V/ns
P _D	T _C = 25°C	1560	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
T _L	1.6mm (0.062 in.) from Case for 10s	300	°C
T _{sold}	Plastic Body for 10s	260	°C
F _c	Mounting Force	30..120/6.7..27	N/lb.
Weight		10	g

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 3mA	1000		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 8mA	3.5		V
I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V			±200 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C			50 μA 3 mA
R _{DS(on)}	V _{GS} = 10V, I _D = 0.5 • I _{D25} , Note 1			220 mΩ

PLUS264™

G = Gate D = Drain
S = Source Tab = Drain

Features

- Low Intrinsic Gate Resistance
- Low Package Inductance
- Fast Intrinsic Rectifier
- Low R_{DS(on)} and Q_G

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- Temperature and Lighting Controls

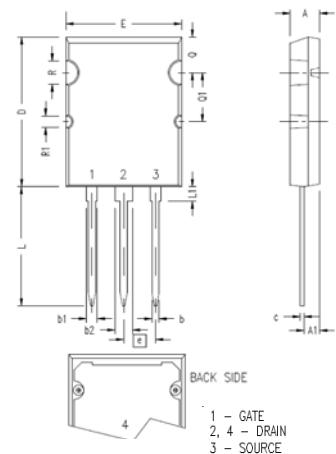
Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
I_{fs}	V _{DS} = 20V, I _D = 0.5 • I _{D25} , Note 1	26	43	S
C_{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	13.6	nF	
C_{oss}		1046	pF	
C_{rss}		86	pF	
R_{GI}	Gate Input Resistance	0.12	Ω	
t_{d(on)}	Resistive Switching Times V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25} R _G = 0.5Ω (External)	48	ns	
t_r		30	ns	
t_{d(off)}		66	ns	
t_f		28	ns	
Q_{g(on)}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25}	264	nC	
Q_{gs}		76	nC	
Q_{gd}		110	nC	
R_{thJC}			0.08 °C/W	
R_{thCS}		0.13	°C/W	

Source-Drain Diode

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
I_s	V _{GS} = 0V		44	A
I_{SM}	Repetitive, Pulse Width Limited by T _{JM}		176	A
V_{SD}	I _F = I _s , V _{GS} = 0V, Note 1		1.4	V
t_{rr}	I _F = 22A, -di/dt = 100A/μs V _R = 100V, V _{GS} = 0V		300	ns
Q_{RM}		2.1	μC	
I_{RM}		16.2	A	

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

PLUS264™ (IXFB) Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215 BSC		5.46 BSC	
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 5,049,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

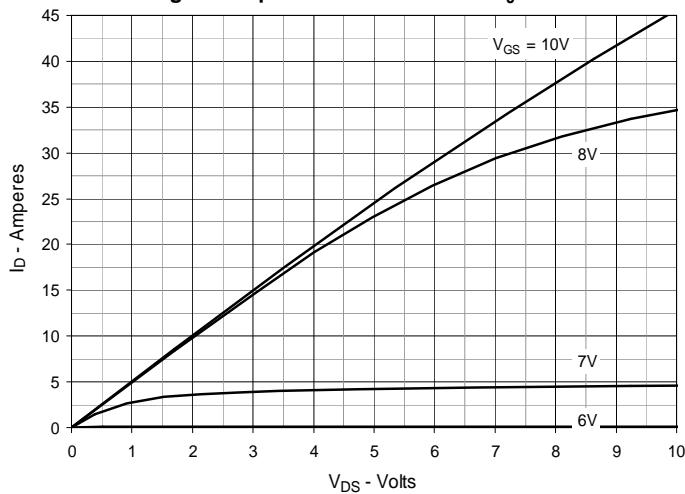
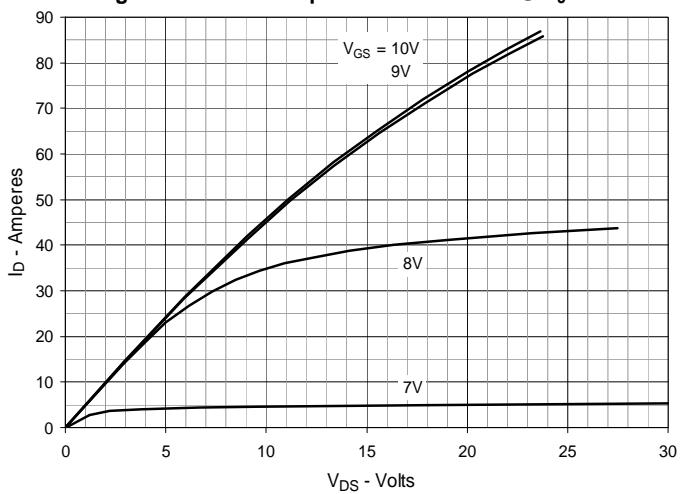
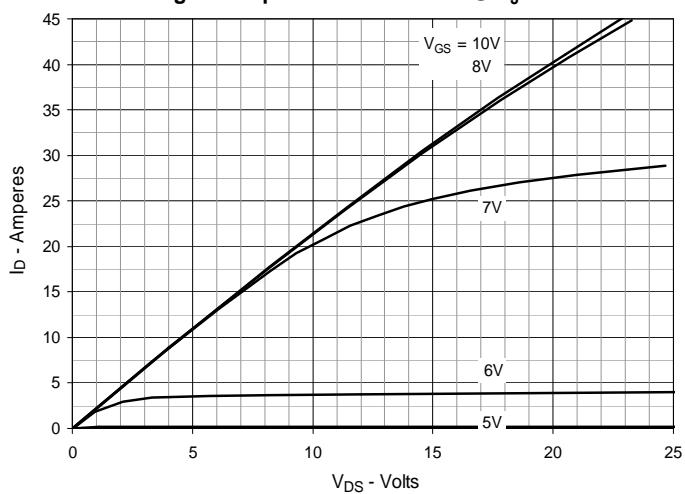
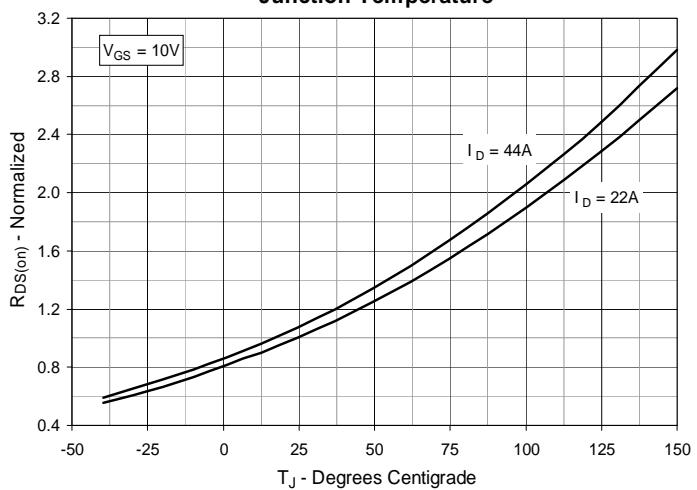
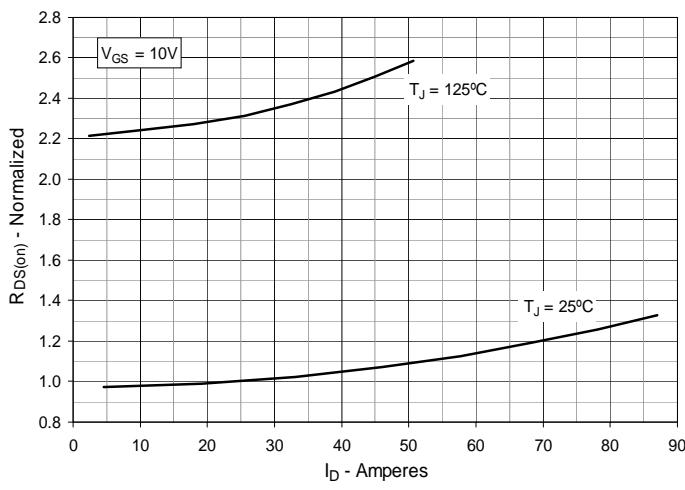
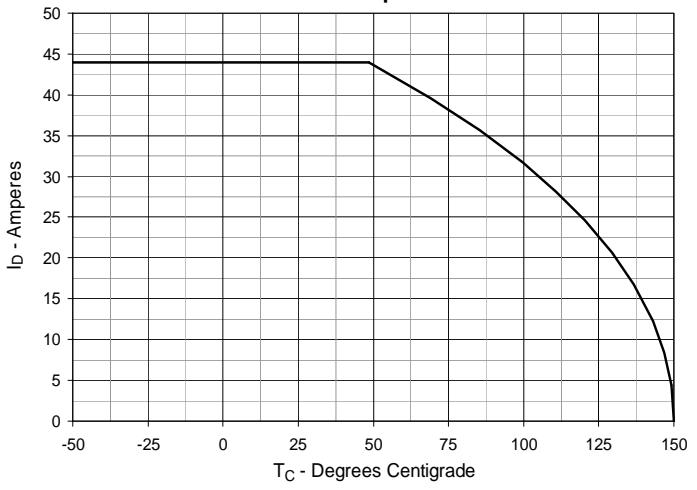
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ **Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$** **Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$** **Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 22\text{A}$ Value vs. Junction Temperature****Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 22\text{A}$ Value vs. Drain Current****Fig. 6. Maximum Drain Current vs. Case Temperature**

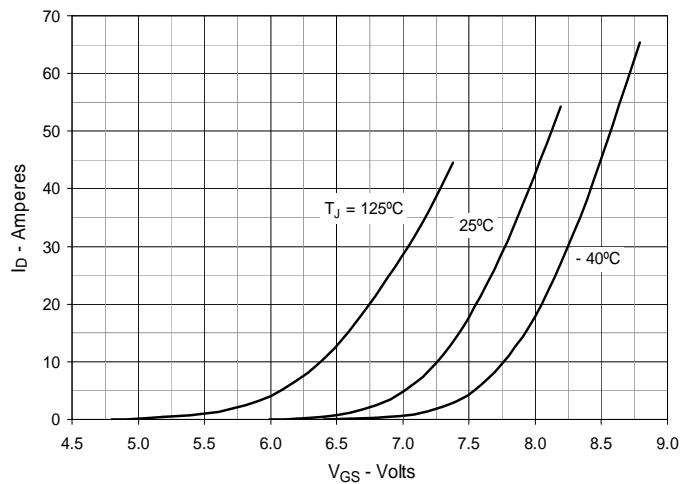
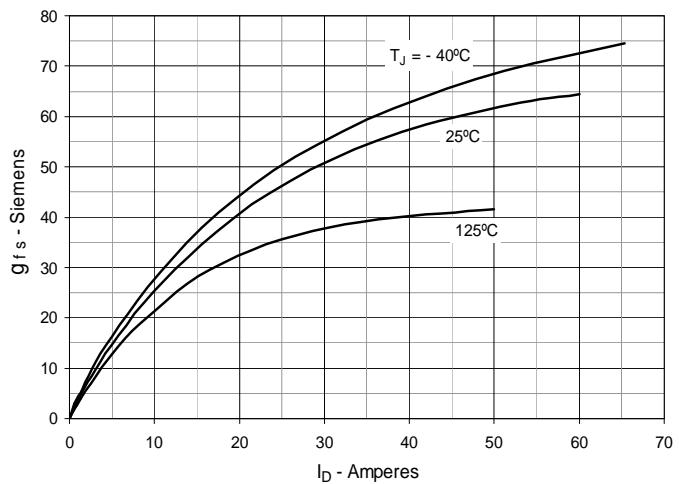
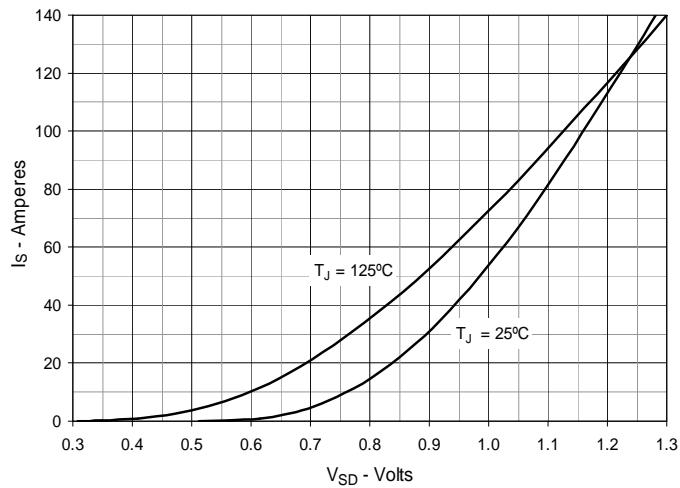
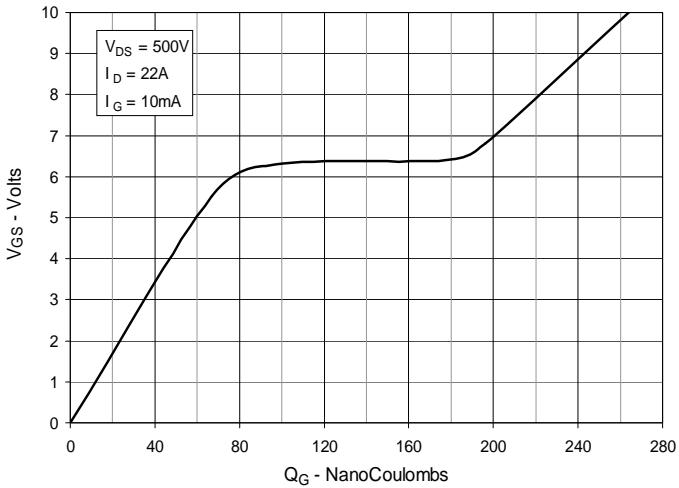
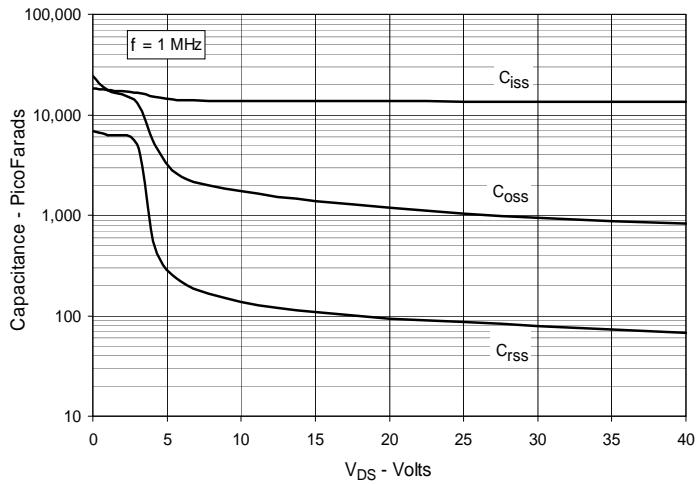
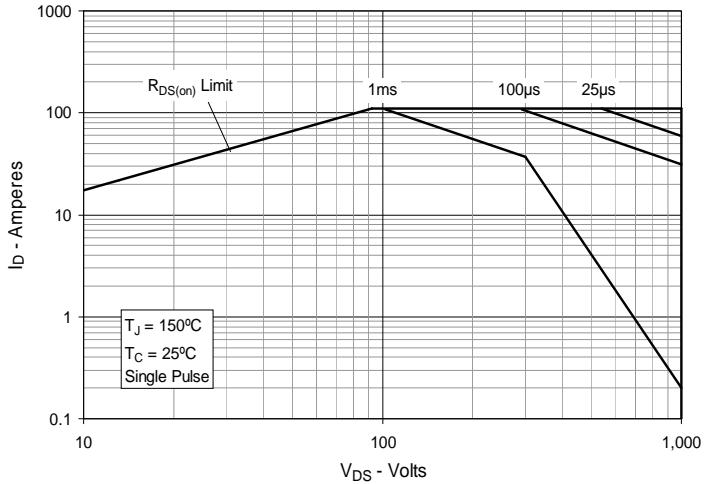
Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Forward Voltage Drop of Intrinsic Diode****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Forward-Bias Safe Operating Area**

Fig. 13. Maximum Transient Thermal Impedance